



Material Content Data Sheet



Sales Product Name		IPB200N25N3 G		Issued		29. August 2013		
MA#		MA000812202						
Package		PG-TO263-3-2		Weight*		1470.38 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	17.562	1.19	1.19	11944	11944
leadframe	non noble metal	iron	7439-89-6	0.853	0.06		580	
	inorganic material	phosphorus	7723-14-0	0.256	0.02		174	
	non noble metal	copper	7440-50-8	851.691	57.93	58.01	579231	579983
wire	non noble metal	aluminium	7429-90-5	11.752	0.80	0.80	7992	7992
encapsulation	organic material	carbon black	1333-86-4	8.549	0.58		5814	
	plastics	epoxy resin	-	94.042	6.40		63957	
	inorganic material	silicondioxide	60676-86-0	467.360	31.78	38.76	317848	387620
leadfinish	non noble metal	tin	7440-31-5	9.657	0.66	0.66	6567	6567
plating	non noble metal	nickel	7440-02-0	0.220	0.01		150	
	inorganic material	phosphorus	7723-14-0	0.023	0.00	0.01	15	165
solder	non noble metal	tin	7440-31-5	0.168	0.01		115	
	noble metal	silver	7440-22-4	0.211	0.01		143	
	non noble metal	lead	7439-92-1	8.043	0.55	0.57	5470	5728
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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